

## Features

- Transient protection for high-speed data lines
  - IEC 61000-4-2 (ESD)  $\pm 25\text{kV}$  (Air)
  - $\pm 17\text{kV}$  (Contact)
  - IEC 61000-4-4 (EFT) 40A (5/50 ns)
  - Cable Discharge Event (CDE)
- Package optimized for high-speed lines
- Ultra-small package (2.5mmx1.0mmx0.55mm)
- Protects four data lines
- Low capacitance: 0.6pF for each channel
- Low leakage current:  $0.1\mu\text{A}@V_{\text{RWM}}$  (Typical)
- Low clamping voltage
- Each I/O pin can withstand over 1000 ESD strikes for  $\pm 8\text{kV}$  contact discharge
- RoHS compliant

## Description

T0514TP is an ultra-low capacitance Transient Voltage Suppressor (TVS) designed to provide electrostatic discharge (ESD) protection for high-speed data interfaces. With typical capacitance of 0.6 pF only, T0514TP is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4 ( $\pm 15\text{kV}$  air,  $\pm 8\text{kV}$  contact discharge), IEC 61000-4-4 (electrical fast transient - EFT) (40A, 5/50 ns), very fast charged device model (CDM) ESD and cable discharge event (CDE), etc.

T0514TP uses ultra-small DFN2510-10L package. Each T0514TP device can protect four high-speed data lines. The combined features of ultra-low capacitance, ultra-small size and high ESD robustness make T0514TP ideal for high-speed data ports and high-frequency lines (e.g., HDMI & DVI) applications. The low clamping voltage of the T0514TP guarantees a minimum stress on the protected IC.

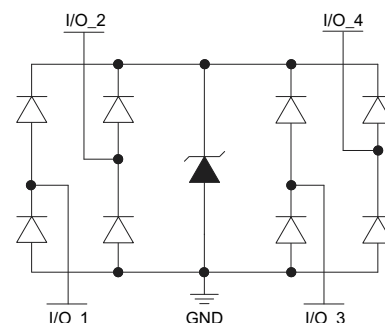
## Applications

- Serial ATA
- PCI Express
- Desktops, Servers and Notebooks
- MDDI Ports
- USB 2.0/3.0/3.1 Power and Data Line Protection
- Display Ports
- High Definition Multi-Media Interface (HDMI)
- Digital Visual Interfaces (DVI)

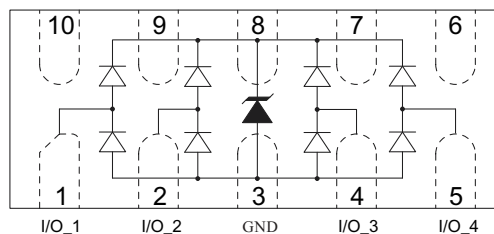
## Mechanical Characteristics

- DFN2510-10L package
- Flammability Rating: UL 94V-0
- Marking: Part number
- Packaging: Tape and Reel

## Circuit Diagram



## Pin Configuration



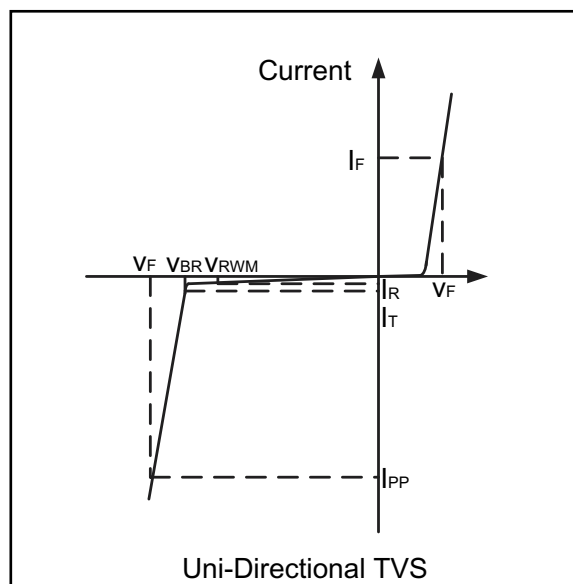
DFN2510-10L  
(Top View)

## Absolute Maximum Rating

Symbol	Parameter	Value	Units
$V_{ESD}$	ESD per IEC 61000-4-2 (Air)	$\pm 25$	kV
	ESD per IEC 61000-4-2 (Contact)	$\pm 17$	
$T_{OPT}$	Operating Temperature	-55/+125	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature	-55/+150	$^{\circ}\text{C}$

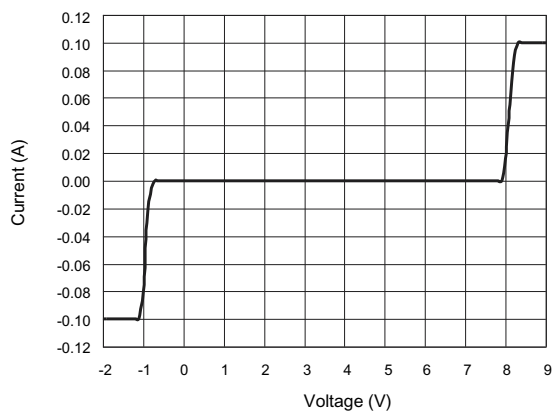
## Electrical Characteristics (T = 25 $^{\circ}\text{C}$ )

Symbol	Parameter
$V_{RWM}$	Nominal Reverse Working Voltage
$I_R$	Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Reverse Breakdown Voltage @ $I_T$
$I_T$	Test Current for Reverse Breakdown
$V_C$	Clamping Voltage @ $I_{PP}$
$I_{PP}$	Maximum Peak Pulse Current
$C_{ESD}$	Parasitic Capacitance
$V_R$	Reverse Voltage
f	Small Signal Frequency
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$

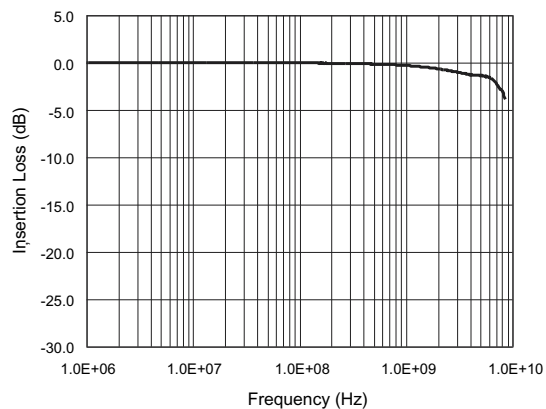


Symbol	Test Condition	Minimum	Typical	Maximum	Units
$V_{RWM}$				5.0	V
$I_R$	$V_{RWM} = 5\text{V}, T = 25^{\circ}\text{C}$ Between I/O and GND		0.1	1.0	$\mu\text{A}$
$V_{BR}$	$I_T = 1\text{mA}$ Between I/O and GND	6.0	8.0	10.0	V
$V_C$	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$ Between I/O and GND			12	V
$C_{ESD}$	$V_R = 0\text{V}, f = 1\text{MHz}$ Between I/O and GND		0.6	0.8	pF
$C_{ESD}$	$V_R = 0\text{V}, f = 1\text{MHz}$ Between I/O and I/O		0.05	0.08	pF

### Voltage Sweeping of I/O to GND

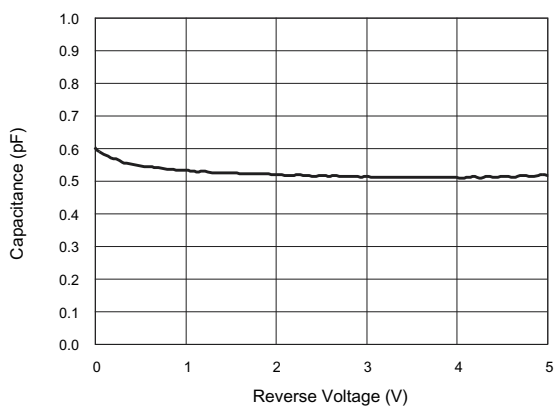


### Insertion Loss S21 of I/O to GND

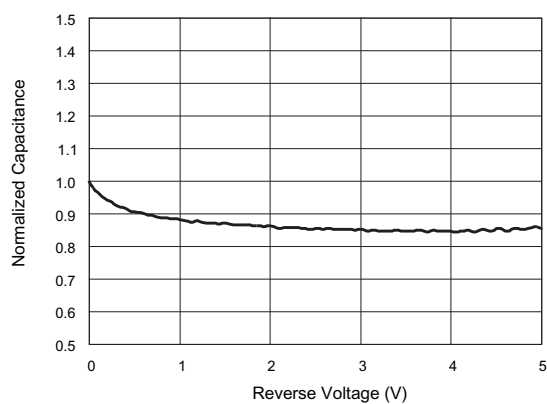


### Capacitance vs. Voltage of I/O to GND (f = 1MHz)

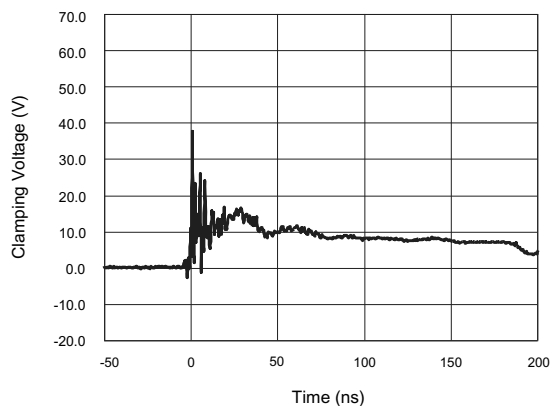
Capacitance vs. Reverse Voltage



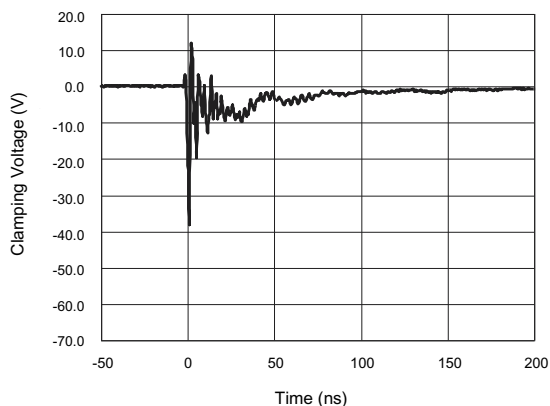
Normalized Capacitance vs. Reverse Voltage



### ESD Clamping of I/O to GND (+8kV Contact per IEC 61000-4-2)



### ESD Clamping of I/O to GND (-8kV Contact per IEC 61000-4-2)



## Application Information

### Pin Connection in PCB

T0514TP provides ESD protection for four data lines simultaneously. The pin connection is shown in the figure below.

Four parallel data lines, from inner IC to I/O port connector, could connect to T0514TP four I/O pins directly. Pin 3&8 of T0514TP is the GND pin, which should connect to the GND of PCB. The wire should be as short as possible in order to minimize the parasitic inductance.

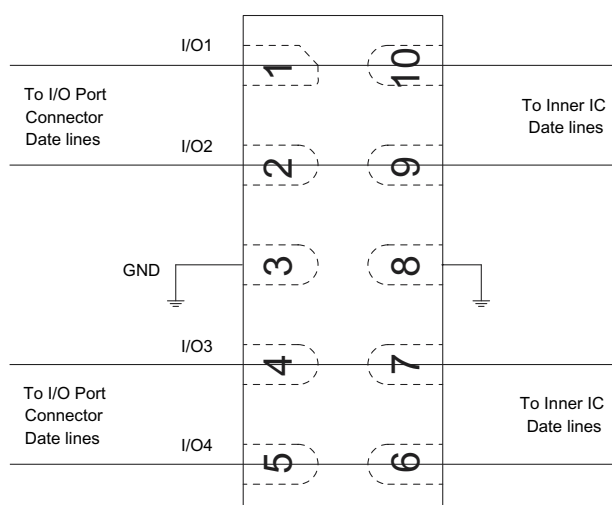


Figure 1 T0514TP pin connection in PCB

### PCB Layout Guidelines

For optimum ESD protection and the whole circuit performance, the following PCB layout guidelines are recommended:

- T0514TP GND pin to the PCB GND rail path should be as short as possible. It could reduce the ESD transient return path to GND.
- The vias connecting T0514TP GND pins to the PCB GND should be wide
- Place T0514TP as close to the connector port as possible. It could reduce the parasitic inductance and restrict ESD coupling into adjacent traces.
- Avoid running critical signals near board edges.

## Application Information

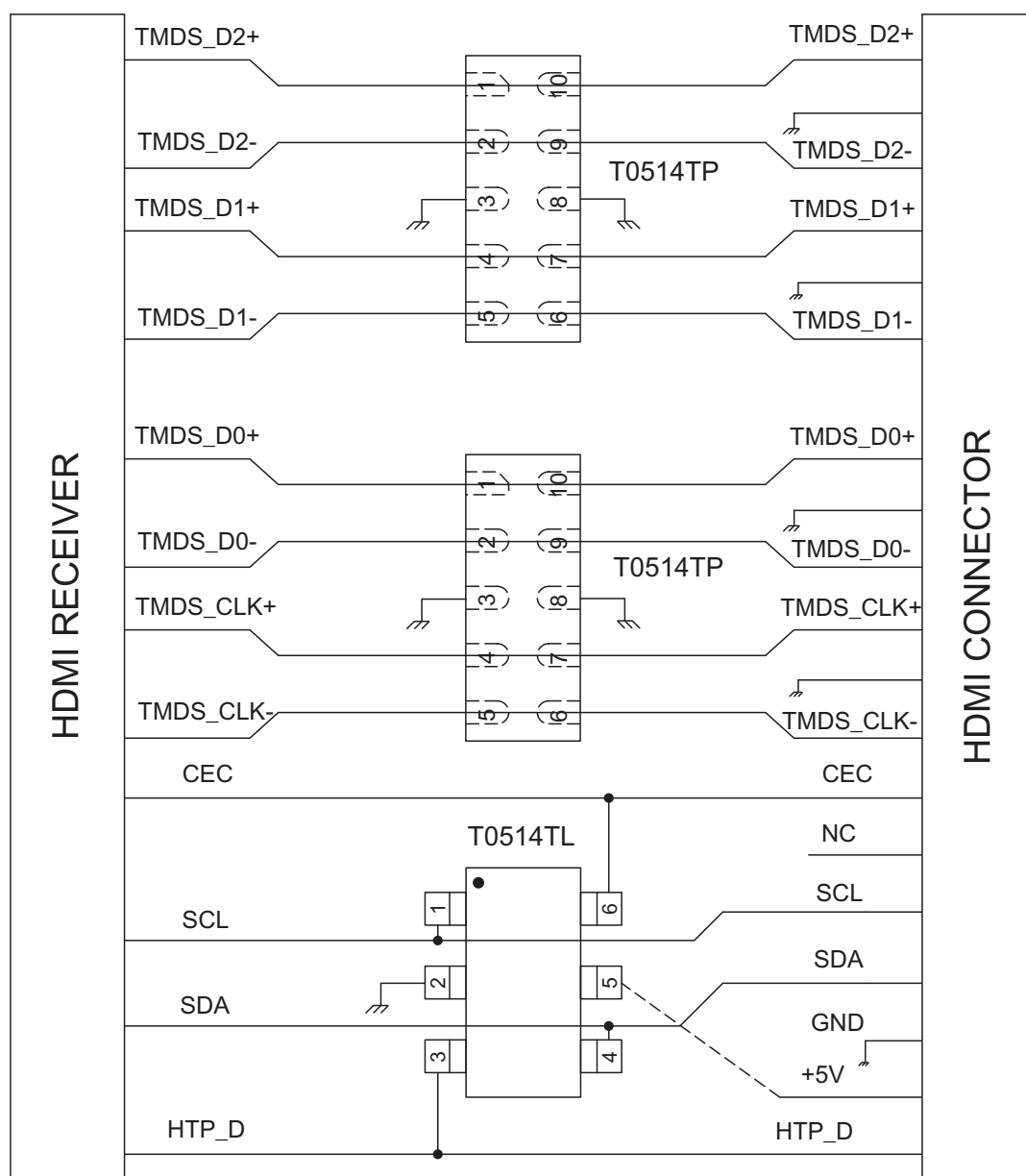
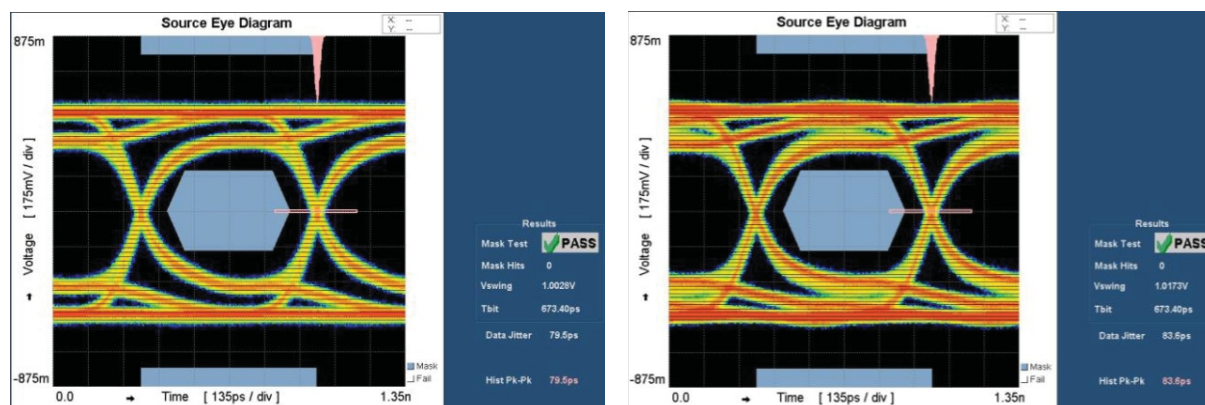


Figure 2 Layout Top View for HDMI Interface With T0514TP & T0514TL

## Application Information

### Eye Diagram Measurements for 1080P HDMI Data Transmission



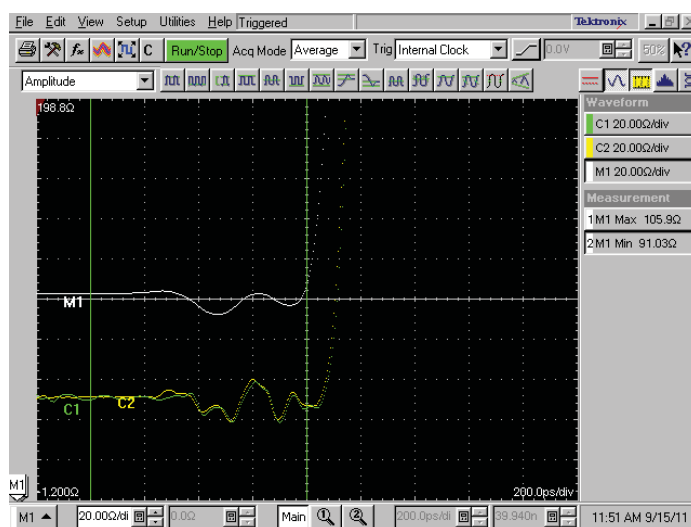
Without TVS

Without T0514TP

Figure 3 Eye Diagram Measurements for 1080P HDMI

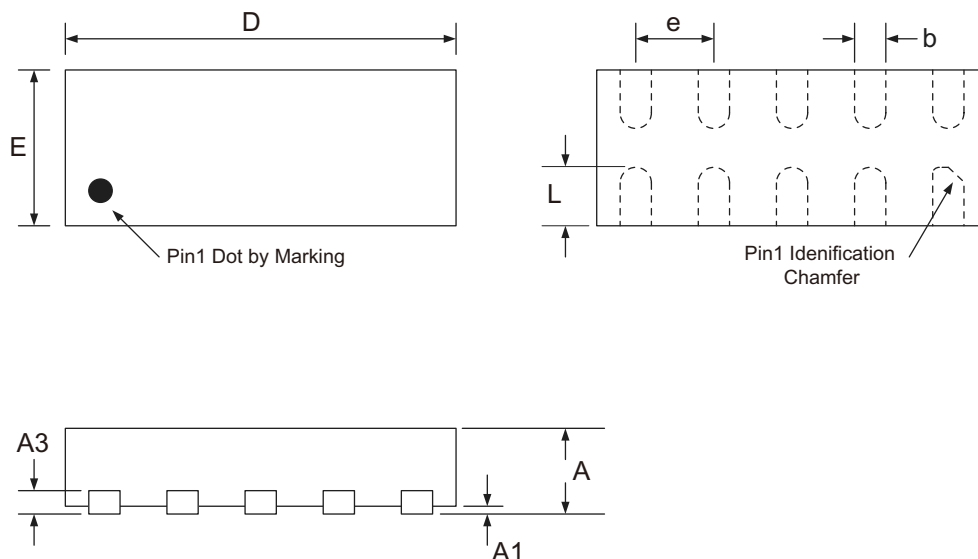
### TDR Measurements for HDMI

The combination of low capacitance, small package, and flow-through design means it is possible to use T0514TP to meet the HDMI impedance requirements of  $100\ \Omega \pm 15\%$ . Figures 4 shows impedance test result for a TDR rise time of 100ps, using a CitrusCOM evaluation board with 100 Ohm differential traces. Measurements Were taken using a TDR method as outlined in the HDMI Compliance Test Specification(CTS). In this case, the device meets the HDMI CTS requirement of  $100\ \Omega \pm 15\%$  with plenty of margin.



## Package Outline

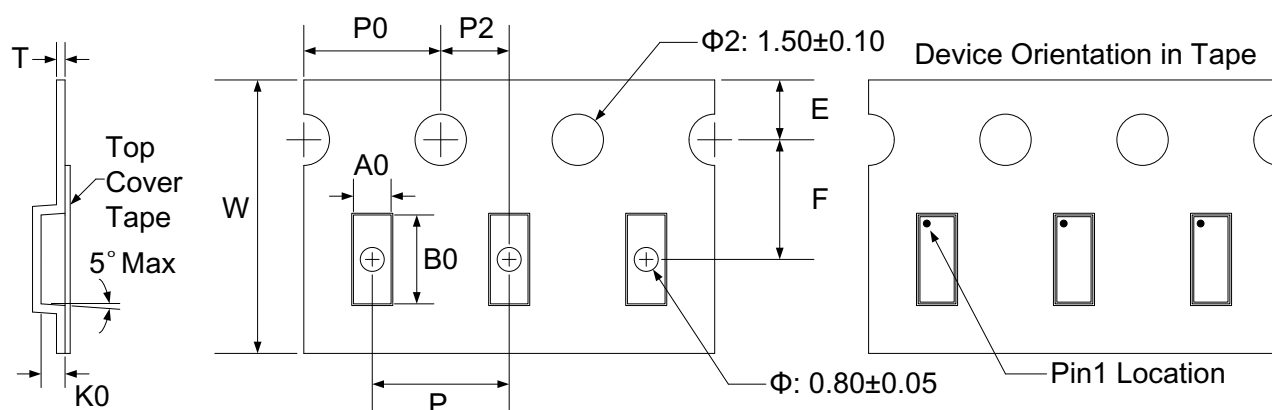
DFN2510-10L package  
Thermally-Enhanced  
MSL-1 Level



Package Dimensions (Controlling dimensions are in millimetres)

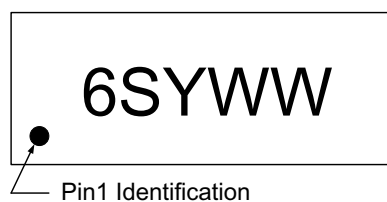
Symbol	Dimensions (mm)		Dimensions (inch)	
	Minimum	Maximum	Minimum	Maximum
A	0.500	0.600	0.020	0.024
A1	0.000	0.050	0.000	0.002
A3	0.150REF.		0.006REF.	
b	0.150	0.250	0.006	0.010
D	2.450	2.550	0.096	0.100
E	0.950	1.050	0.037	0.041
e	0.500 BSC		0.020 BSC	
L	0.300	0.400	0.012	0.016

## Tape and Reel Specification

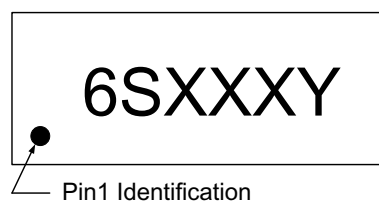


Symbol	W	A0	B0	K0	E	F	P	P0	P2	T
Dimensions (mm)	8.00+0.3 -0.1	1.23±0.05	2.7±0.05	0.7±0.05	1.75±0.1	3.5±0.05	4.0±0.1	4.0±0.1	2.0±0.05	0.25±0.02

## Marking Codes



Or



Note:

(1) "6S" is part number, while "YWW" is date code.

Note:

(1) "6S" is part number, fixed.

(2) "XXX" is the last 3 characters of the wafer's Lot No.,  
"Y" is the internal code.

## Ordering Information

Part Number	Working Voltage	Quantity Per Reel	Reel Size
T0514TP	5V	3,000	7 Inch



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